



## Materials Declaration Form

<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b> <b>Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2020-07-31</b>
<b>Company Unique ID</b>	<b>NL 008751171B01</b>		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>Giovanni Giacopello</b>	<b>Representative Title</b>	<b>ADG MD CHAMPION</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement		
<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>
		<b>Standard</b>

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SM6T12A	HHZJ*TWU012D	A	9941	2020-07-31
	Amount	UoM	Unit type	ST ECOPACK Grade
	98	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

  
 life.augmented

Package Designator	Size	Nbr of instances	Shape	
SOJ	3X3X0.9	2	J bend	
Comment	Package: SMB CLIP (SOD 6 NEW)			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.02	Die	173
Lead	2.61	Soft solder	26592

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	2.61	Soft solder	26592
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	2.61	Soft solder	2606000

Material Composition Declaration :						Mfr Item Name	HHZJ*TWU012D					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.623	mg	supplier	die	Silicon (Si)	7440-21-3		1.573	mg	969193	16051
				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	5545	92
				supplier	metallization	Gold (Au)	7440-57-5		0.007	mg	4313	71
				supplier	metallization	Nickel (Ni)	7440-02-0		0.007	mg	4313	71
				supplier	Passivation	Silicon Oxide	7631-86-9		0.009	mg	5546	94
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.006	mg	3697	61
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1232	20
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.010	mg	6161	102
Leadframe & Clip	M-004 Copper and its alloys	39.382	mg	supplier	alloy	Copper (Cu)	7440-50-8		39.362	mg	999492	401653
				supplier	alloy	Iron (Fe)	7439-89-6		0.004	mg	102	41
				supplier	alloy	Phosphorus metal	7723-14-0		0.014	mg	355	143
				supplier	alloy	Zinc (Zn)	7440-66-6		0.002	mg	51	20
Soft solder	Solder	2.817	mg	SVHC	solder	Lead (Pb)	7439-92-1		2.606	mg	925098	26592
				supplier	solder	Tin (Sn)	7440-31-5		0.141	mg	50053	1439
				supplier	solder	Silver (Ag)	7440-22-4		0.070	mg	24849	714
Encapsulation	M-011 Other inorganic materials	52.433	mg	supplier	mold compound	silica fused	7631-86-9		38.800	mg	739992	395918
				supplier	mold compound	silica quartz	14808-60-7		10.485	mg	199969	106990
				supplier	mold compound	phenolic resin	9003-35-4		2.623	mg	50026	26765
				supplier	mold compound	carbon black	1333-86-4		0.525	mg	10013	5357
connections coating	Solder	1.745	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.745	mg	1000000	17806